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Semiconductor Manufacturing International Corporation
中 芯 國 際 集 成 電 路 製 造 有 限 公 司 *

(Incorporated in the Cayman Islands with limited liability)

(Stock Code: 981)

COMPLETION OF THE ISSUE OF US$600 MILLION 2.693% BONDS DUE 2025

Joint Global Coordinators, Joint Lead Managers and Joint Bookrunners

J.P.Morgan

Joint Lead Managers and Joint Bookrunners

The Company is pleased to announce that completion of the issue of the Bonds in the principal amount of US$600 million took place on 27 February 2020.

Reference is made to the announcements of the Company dated 19 February 2020 and 20 February 2020 relating to, among other things, the proposed issue of the Bonds (the "Announcements"). Unless the context otherwise requires, capitalised terms in this announcement shall have the same meanings as those defined in the Announcements.

The Company is pleased to announce that completion of the issue of the Bonds in the principal amount of US$600 million took place on 27 February 2020. The Company has received approval in-principle from the SGX-ST for the listing and quotation of the Bonds. The Bonds are listed on the SGX-ST on 28 February 2020. The approval in-principle granted for the listing and quotation of the Bonds is not to be taken as an indication of the merits of the Company or any other subsidiary or associated company of the Company or the Bonds. The estimated net proceeds (net of fees, commissions and expenses) from the issue of the Bonds will be approximately US$596.4 million.

By order of the Board
Semiconductor Manufacturing International Corporation
Gao Yonggang
Executive Director, Chief Financial Officer and Joint Company Secretary

Shanghai, PRC
28 February 2020

As at the date of this announcement, the Directors of the Company are:

Executive Directors
ZHOU Zixue *(Chairman)*
ZHAO Haijun *(Co-Chief Executive Officer)*
LIANG Mong Song *(Co-Chief Executive Officer)*
GAO Yonggang *(Chief Financial Officer and Joint Company Secretary)*

Non-executive Directors
CHEN Shanzhi
ZHOU Jie
REN Kai
LU Jun
TONG Guohua

Independent Non-executive Directors
William Tudor BROWN
CONG Jingsheng Jason
LAU Lawrence Juen-Yee
FAN Ren Da Anthony
YOUNG Kwang Leei

* *For identification purposes only*